



Call for papers EIPC Summer Conference Leoben 2019

Date: June 13 & 14, 2019

Conference location: Falkensteiner Hotel & Asia Spa Leoben

Bonus Programme: Visit to AT&S Leoben

Presentations on the following topics can be included in the conference programme:

Keynote / Trends

- Business Outlook: Global Electronics Industry
- Automotive, E-mobility and High Rel application, Industry Roadmap
- Medical Industrial Electronics, Aerospace, Avionics-G5, Antenna application

Reliability /traceability requirements by Application

- Responsibility for Product Reliability and Safety
- Standards for Product Safety and Reliability
- Inhouse process control and conformation Testing
- Material and finish product Safety and Testing
- Advanced supply chain and Third party Testing
- Tools for Testing and ensuring product safety and reliability

Design & New Technologies

Success through Evolution- or Disruptive Technologies?

- PCBs in Polymer Technology
- Printed Electronics / 3D Electronics
- Material Technology- Laminate technologies - Coating technologies

Equipment evolution to meet Technology challenges

- Automation
- Imaging and Printing
- ML-Pressing
- Controlled line etching, Copper thickness tolerances
- Embedding and Metal Core PCBs
- New technology, Innovations and Invention
- Laser, Mechincal drilling

Roadmapping on Automotive, Medical, Aerospace & Industrial

- What input is provided through "Roadmap by market segments"
- Technology Guidance through market needs
- Adapting processes, materials, chemistry, equipments to future technology needs
- Strategic Partnership and planning for success through Networking

Most common used abbreviations in the PCB Indsutry

- 'SLP' (Substrates like PCB) are used in Asia for HDI PCBs in any layer technology
- 'PLP' (Panel Level Packaging) to reduce cost in WLP Wafer Level Packaging
- 'SLP utilising MSAP' (modified Semi- Additive processes)
- 'TSP' (Touch Screen Panel) and integrated touch OLED displays offers new types of PCBs
- 'ELIC' (Every Layer Interconnected) as right and regid flex



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CALL FOR PAPERS

EIPC Summer Conference Leoben – Jun 13 & 14, 2019

<p>Topics We invite you to submit a paper for one of the following topics:</p> <p>Keynote / Trends -Business Outlook: Global Electronics Industry -Automotive, E-mobility and High Rel application, Industry Roadmap -Medical Industrial Electronics, Aerospace, Avionics-G5, Antenna application</p> <p>Reliability /traceability requirements by Application -Responsibility for Product Reliability and Safety -Standards for Product Safety and Reliability -Inhouse process control and conformation Testing -Material and finish product Safety and Testing -Advanced supply chain and Third party Testing -Tools for Testing and ensuring product safety and reliability</p> <p>Design & New Technologies Success through Evolution- or Disruptive Technologies? -PCBs in Polymer Technology -Printed Electronics / 3D Electronics -Material Technology- Lamine technologies - Coating technologies</p> <p>Equipment evolution to meet Technology challenges -Automation -Imaging and Printing -ML-Pressing -Controlled line etching, Copper thickness tolerances -Embedding and Metal Core PCBs -New technology, Innovations and Invention -Laser, Mechincal drilling</p> <p>Roadmapping on Automotive, Medical, Aerospace & Industrial -What input is provided through "Roadmap by market segments" -Technology Guidance through market needs -Adapting processes, materials, chemistry, equipments to future technology needs -Strategic Partnership and planning for success through Networking</p> <p>Most common used abbreviations in the PCB Indsuty 'SLP' (Substrates like PCB) are used in Asia for HDI PCBs in any layer technology 'PLP' (Panel Level Packaging) to reduce cost in WLP Wafer Level Packaging 'SLP utilising MSAP' (modified Semi- Additive processes) 'TSP' (Touch Screen Panel) and integrated touch OLED displays offers new types of PCBs 'ELIC' (Every Layer Interconnected) as right and rigid flex Any other topic you feel may be of interest</p> <p>Notes for speakers The following guidelines are provided regarding the submittal of papers and how they are to be presented at the Conference:</p> <ul style="list-style-type: none"> • Papers should supply new technical, management or statistical information and not be presented for commercial purpose 	<ul style="list-style-type: none"> • All presentations should be made in English. If the author has problems with presenting in English, he or she should inform EIPC about this situation. • Presentations should not make direct comparisons with competitors' products. • When the description of particular equipment is necessary for proper understanding of the process, it shall be confined to technical aspects. • Presentations will be required as a WRITTEN TEXT (Word/PDF) file • Illustrations, graphics, tables or pictures (including presenter's photograph) have to be electronically delivered in standard format and in the appropriate resolution (75 dpi for electronic publication) <p>The author or presenter of an oral presentation will be offered a complimentary one day conference registration, valid on the day the author is invited to present.</p> <p>Abstract guidelines Abstracts should include the following:</p> <ul style="list-style-type: none"> • Title of Presentation • Author Listing; first/last name, affiliation, mailing address, telephone, fax, e-mail • Abstract text (max. 200 words) • Biography: brief background on the principal/presenting author (max. 100 words) <p>Acceptance Criteria Abstracts will be reviewed by the Programme Committee, consisting of experts from within our industry. The official language of the Conference is English, NO simultaneous translations will be provided. Selections will be based on the following criteria:</p> <ul style="list-style-type: none"> • Contribution to the industry. • The abstract should clearly describe the nature, content, key points, and significance of the proposed paper. • Presentations are to be strictly non-commercial and must focus on technical merits of described processes. • Proprietary and/or confidentiality issues as well as approvals should be determined at time of submission. <p>Deadlines</p> <ul style="list-style-type: none"> • 1 page Abstract: March 11, 2019 • Paper submission: May 20, 2019 <p>Please send the abstract submission form to: Mrs. K. Smit-Westenberg email: kwestenberg@eipc.org</p> <p>Sponsors:</p> <div style="display: flex; justify-content: space-around; align-items: flex-end;"> <div style="text-align: center;">  <p>PLUS the leading source for the PCB industry</p> </div> <div style="text-align: center;">  <p>DPS Poisné spoje a A do Z</p> </div> <div style="text-align: center;">  <p>evertiq™ online european electronics</p> </div> <div style="text-align: center;">  <p>emsnow the global source for the electronic manufacturing services industry</p> </div> <div style="text-align: center;">  <p>PCB 007 the real-time online magazine</p> </div> </div> <p>For more information about sponsor possibilities please have a look at the EIPC website www.eipc.org</p> <p>Enquiries Please send registration and / or sponsor enquiries to: Mrs. K. Smit-Westenberg, email: kwestenberg@eipc.org</p>
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